

[Document] Abstract

[Abstract]

[Object]

To provide a semiconductor device in which reflow cracks do not occurs, and
5 high reliability is assured.

[Construction] Bonding a semiconductor chip on lead frames via filmy organic
die bonding material, followed by packaging the semiconductor chip with
sealing resin. Then a semiconductor device is fabricated.

10

[Effect] Occurrence of reflow crack can be eliminated during the soldering
reflow process of the semiconductor packaging, and thereby a highly reliable
semiconductor can be fabricated.

15 [Selected Drawings]

None